

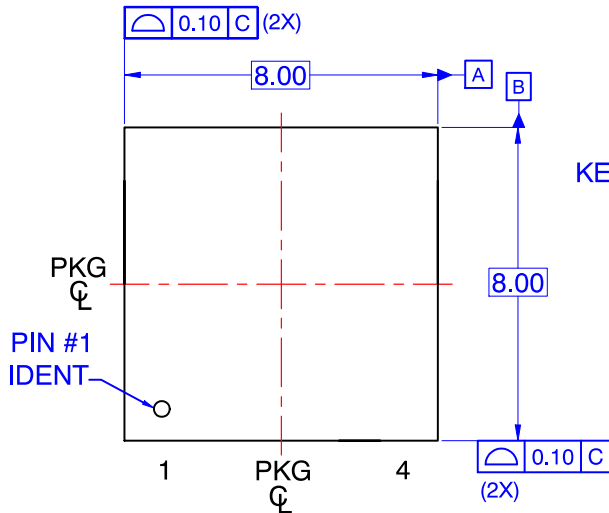
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

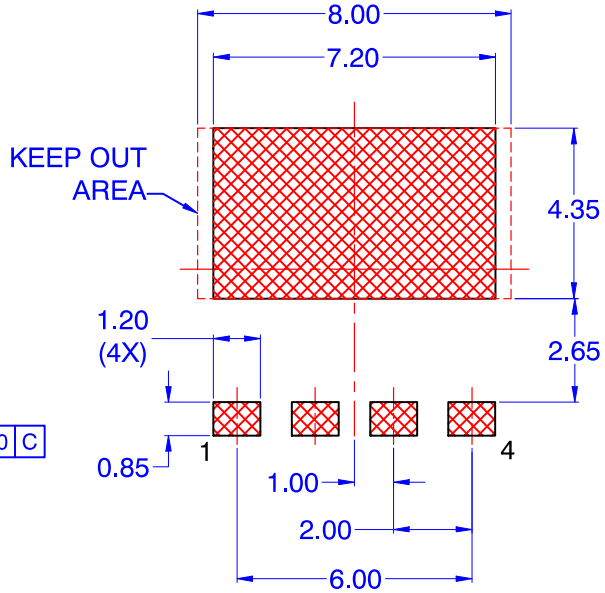


PQFN4 8X8, 2P
CASE 483AP
ISSUE O

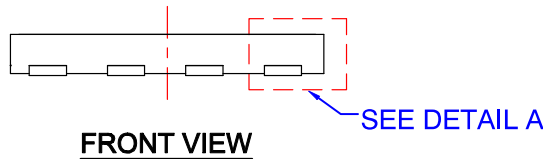
DATE 30 SEP 2016



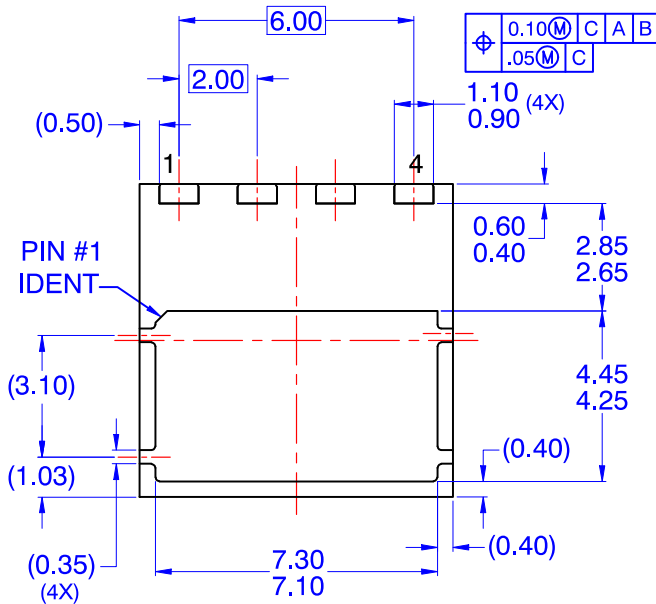
TOP VIEW



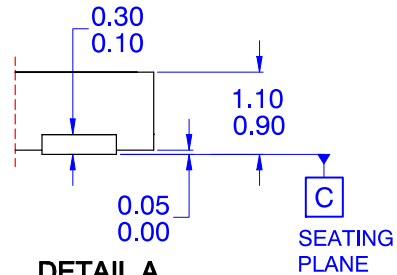
LAND PATTERN RECOMMENDATION



FRONT VIEW



BOTTOM VIEW



DETAIL A
 SCALE: 2X

- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE IS NOT PRESENTLY REGISTERED WITH ANY STANDARDS COMMITTEE.
 - B) DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR PROTRUSIONS.
 - C) ALL DIMENSIONS ARE IN MILLIMETERS.
 - D) DRAWING CONFORMS TO ASME Y14.5M-1994.

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